

Product / Process Change Notification



N° 2019-025-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Capacity extension and chip top harmonization at Infineon Technologies wafer fab in Sdn. Bhd., Kulim, Malaysia for dedicated OptiMOS™3 products in MG-WDSO packages

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **15th January 2020**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: “**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Product / Process Change Notification



N° 2019-025-A

► **Products affected:**

Please refer to attached affected product list 1_cip19025_a

► **Detailed Change Information:**

Subject: Extension of 200mm wafer production capacity for OptiMOS™3 at Infineon Technologies Sdn. Bhd., Kulim, Malaysia and harmonization of chip top metal stack

Reason:

- Implementation of second production site to support continuously increasing customer demand in the future and
- Optimization of MG-WDSO assembly process by reduction of chip top metallization complexity

Description:	<u>Old</u>	<u>New</u>
Wafer production	<ul style="list-style-type: none">■ Infineon Technologies AG, Regensburg, Germany	<ul style="list-style-type: none">■ Infineon Technologies AG, Regensburg, Germany and <ul style="list-style-type: none">■ Infineon Technologies Sdn. Bhd., Kulim, Malaysia
Metal stack	<ul style="list-style-type: none">■ AlSiCu/Cu	<ul style="list-style-type: none">■ TiTiNWAICu/TiWCu

► **Product Identification:**

Internal traceability assured via Baunumber, Lotnumber and date code

External traceability assured via Waferlot number printed on Barcode Product Label

► **Impact of Change:**

NO change in electrical and thermal datasheet parameters as proven via product characterization.

NO change in quality and reliability verified within product qualification. Processes are optimized to meet product performance according to already applied Infineon specification.

NO changes in bill of material only change in the chip top metal thickness

► **Attachments:**

Affected product list 1_cip19025_a

Product / Process Change Notification



N° 2019-025-A

► Time Schedule:

- | | |
|-------------------------------|--|
| ■ Final qualification report: | Available |
| ■ First samples available: | on request |
| ■ Intended start of delivery: | 01-02-2020 or earlier based on customer approval |

If you have any questions, please do not hesitate to contact your local Sales office.

PCN N° 2019-025-A

Capacity extension and chip top harmonization at Infineon Technologies wafer fab in Sdn. Bhd.,
Kulim, Malaysia for dedicated OptiMOS™3 products in MG-WDSO packages



Sales name	SP number	OPN	Package
BSB044N08NN3 G	SP000604542	BSB044N08NN3GXUMA1	MG-WDSO-2
BSB056N10NN3 G	SP000604540	BSB056N10NN3GXUMA1	MG-WDSO-2
BSB104N08NP3 G	SP001164330	BSB104N08NP3GXUSA1	MG-WDSO-2
BSB165N15NZ3 G	SP000617000	BSB165N15NZ3GXUMA1	MG-WDSO-2
BSB280N15NZ3 G	SP000604534	BSB280N15NZ3GXUMA1	MG-WDSO-2
BSF134N10NJ3 G	SP000604536	BSF134N10NJ3GXUMA1	MG-WDSO-2
BSF450NE7NH3	SP001019350	BSF450NE7NH3XUMA1	MG-WDSO-2